

# 2.5V Drive Nch MOS FET

AEC-Q101 Qualified

## RTQ035N03FRA

**●Structure**

Silicon N-channel MOS FET

**●Features**

- 1) Low On-resistance.
- 2) Space saving, small surface mount package (TSMT6).
- 3) Low voltage drive (2.5V drive).

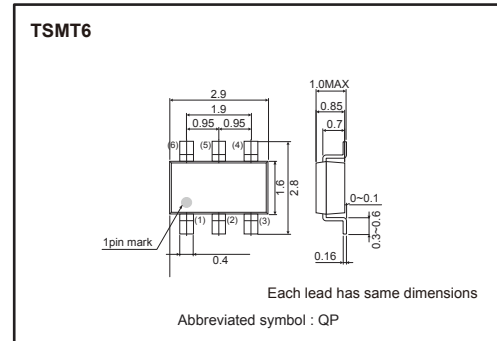
**●Applications**

Switching

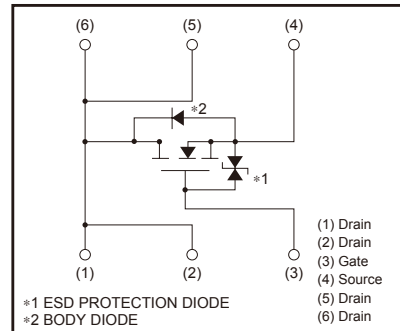
**●Packaging specifications**

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
RTQ035N03FRA		○

**●External dimensions (Unit : mm)**



**●Inner circuit**



**●Absolute maximum ratings (Ta=25°C)**

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DSS</sub>	30	V	
Gate-source voltage	V <sub>GSS</sub>	12	V	
Drain current	Continuous	I <sub>D</sub>	±3.5	A
	Pulsed	I <sub>DP</sub> *1	±15	A
Source current (Body diode)	Continuous	I <sub>S</sub>	1.0	A
	Pulsed	I <sub>SP</sub> *1	4.0	A
Total power dissipation	P <sub>D</sub> *2	1.25	W	
Channel temperature	T <sub>ch</sub>	150	°C	
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

\*1 Pw≤10μs, Duty cycles≤1%  
 \*2 Mounted on a ceramic board

**●Thermal resistance**

Parameter	Symbol	Limits	Unit
Channel to ambient	R <sub>th(ch-a)</sub> *	100	°C/W

\* Mounted on a ceramic board

## Transistors

## ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	–	–	10	$\mu A$	$V_{GS}=12V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	–	–	V	$I_D=1mA, V_{GS}=0V$
Zero gate voltage drain current	$I_{DSS}$	–	–	1	$\mu A$	$V_{DS}=30V, V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	0.5	–	1.5	V	$V_{DS}=10V, I_D=1mA$
Static drain-source on-state resistance	$R_{DS(on)}$ *	–	38	54	$m\Omega$	$I_D=3.5A, V_{GS}=4.5V$
		–	40	56	$m\Omega$	$I_D=3.5A, V_{GS}=4.0V$
		–	55	77	$m\Omega$	$I_D=3.5A, V_{GS}=2.5V$
Forward transfer admittance	$ Y_{fs} $ *	3.0	–	–	S	$V_{DS}=10V, I_D=3.5A$
Input capacitance	$C_{iss}$	–	285	–	pF	$V_{DS}=10V$
Output capacitance	$C_{oss}$	–	90	–	pF	$V_{GS}=0V$
Reverse transfer capacitance	$C_{rss}$	–	55	–	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}$ *	–	8	–	ns	$V_{DD}\doteq 15V$
Rise time	$t_r$ *	–	12	–	ns	$I_D=1.75A$
Turn-off delay time	$t_{d(off)}$ *	–	29	–	ns	$V_{GS}=4.5V$
Fall time	$t_f$ *	–	13	–	ns	$R_L=8.57\Omega$
Total gate charge	$Q_g$ *	–	4.6	6.4	nC	$V_{DD}\doteq 15V$
Gate-source charge	$Q_{gs}$ *	–	0.7	–	nC	$V_{GS}=4.5V$
Gate-drain charge	$Q_{gd}$ *	–	1.5	–	nC	$I_D=3.5A$

\*Pulsed

## ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	$V_{SD}$ *	–	–	1.2	V	$I_S=4A, V_{GS}=0V$

\*Pulsed

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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[Distribution Inventory](#)

Part Number	RTQ035N03FRA
Package	TSMT6
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes

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